



12 Output LVPECL Fanout Buffer

Features

- → 12 Differential LVPECL outputs
- → 2 Selectable reference inputs support either single-ended or differential
- → Up to 2GHz output frequency
- → Ultra low additive phase jitter: < 0.01 ps (typ) (differential 156.25MHz, 12KHz to 20MHz integration range)
- → Low skew between outputs
- → Low delay from input to output
- → Separate Input and output supply voltage for level shifting
- \rightarrow 2.5V / 3.3V power supply
- → Industrial temperature support
- → TQFN-40 package

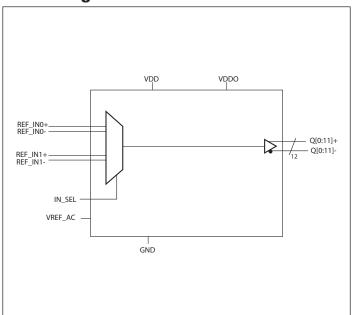
Description

The PI6C5912012 is a high performance LVPECL fanout buffer device which supports up to 2GHz frequency. This device is ideal for systems that need to distribute low jitter LVPECL clock signals to multiple destinations.

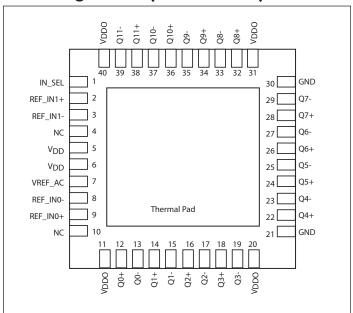
Applications

- → Networking systems including switches and routers
- → High frequency backplane based computing and telecom platforms

Block Diagram



Pin Configuration (40-Pin TQFN)







Pin Description

Pin #	Pin Name	T	ype	Description		
1	IN_SEL	Input	Pulldown	Input clock select. See Table 1 for function. LVCMOS/LVTTL interface levels.		
2.2	REF_IN1+			Reference input 1. Accepts Differential		
2,3 REF_IN1-		- In	put	or Single Ended inputs		
4, 10	NC		-	No Connect		
5, 6	VDD	Po	ower	Core power supply		
7	VREF_AC	Ou	ıtput	Bias voltage output.		
0.0	REF_IN0-			Reference input 0. Accepts Differential		
8, 9	REF_IN0+	- In	put	or Single Ended inputs		
11, 20, 31, 40	VDDO	Po	ower	Output power supply		
12 12	Q0+	0	-44	IVDECL autout a die 0		
12, 13	Q0-		ıtput	LVPECL output pair 0.		
14 15	Q1+	0	4. 4	IVIDECL 1 1 1		
14, 15	Q1-	Ot	ıtput	LVPECL output pair 1.		
16.15	Q2+			AND CO		
16, 17	16, 17 Q2-		ıtput	LVPECL output pair 2.		
10.10	Q3+			IMPEGIA A A A A		
18, 19	Q3-	Ot	ıtput	LVPECL output pair 3.		
21, 30	GND	Po	ower	Power supply ground		
22.22	Q4+			IMPEGIA A A A A		
22, 23	Q4-	Ot	ıtput	LVPECL output pair 4.		
24.25	Q5+			IMPEGIA A A S E		
24, 25	Q5-	Ot	ıtput	LVPECL output pair 5.		
26.25	Q6+			TAIDEOL		
26, 27	Q6-	Ot	ıtput	LVPECL output pair 6.		
20, 20	Q7+			IVDECL autom to a 7		
28, 29	Q7-	Ot	ıtput	LVPECL output pair 7.		
22 22	Q8+			IVDECLtt a.: 0		
32, 33	Q8-		ıtput	LVPECL output pair 8.		
24.25	Q9+			TAIDEOL 1 1 2		
34, 35	Q9-	Ou	ıtput	LVPECL output pair 9.		
26.25	Q10+			AND CLASSIC CONTRACTOR OF THE		
36, 37	Q10-	Ou	ıtput	LVPECL output pair 10.		





Pin Description Cont.

Pin #	Pin Name	Туре	Description
29, 20	Q11+	Outmut	IVDECI output main 11
38, 39	Q11-	Output	LVPECL output pair 11.
Thermal pad	-	-	Thermal pad. Connect to ground.

Function Table

Table 1: Input select function

IN_SEL	Function
0 (default)	REF_IN0 is the selected reference input
1	REF_IN1 is the selected reference input

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
$C_{_{\mathrm{IN}}}$	Input Capcitance			2		pF
R _{PULLDOWN}	Input Pulldown Resistor			200		kΩ
R _{PULLUP}	Input Pullup Resistor			200		kΩ





Maximum Ratings (Above which the useful life may be impaired. For user guidelines, not tested)

Storage temperature55 to +150°C
Supply Voltage to Ground Potential $(V_{DD,}V_{DDO})$ 0.5 to +4.6V
Inputs (Referenced to GND)0.5 to $V_{\scriptscriptstyle DD}$ +0.5V
Clock Output (Referenced to GND)0.5 to $\rm V_{DD}$ +0.5V
Latch up200mA
ESD Protection (Input)2000 V min (HBM)
ESD Protection (Input) 1000 V min (CDM)

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Power Supply Characteristics and Operating Conditions

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
***	Com Comple Wells on		3.135	3.3	3.465	V
V _{DD} Core Supply Voltage		2.375	2.5	2.625	V	
	Output Supply Voltage		3.135	3.3	3.465	V
V_{DDO}			2.375	2.5	2.625	V
I_{EE}	Supply Internal Current			89	105	mA
I_{DD}	Core Power Supply Current			69	80	
T _A	Ambient Operating Temperature		-40		85	°C

DC Electrical Specifications - Differential Inputs

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
I_{IH}	Input High current	Input = V _{DD}			85	uA
I _{IL}	Input Low current	Input = GND	-85			uA
V _{IH}	Input high voltage				V _{DD} +0.3	V
V _{IL}	Input low voltage		-0.3			V
V _{ID}	Input Differential Amplitude PK-PK		0.1			V
V _{CM}	Common model input voltage		GND + 0.5		V _{DD} -0.85	V
ISO _{MUX}	MUX isolation			-89		dBc

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DC Electrical Specifications - LVCMOS Inputs

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
I_{IH}	Input High current	Input = V _{DD}			50	uA
I_{IL}	Input Low current	Input = GND	-50			uA
V_{IH}	Input high voltage	V _{DD} =3.3V	2.0		V _{DD} +0.3	V
V_{IL}	Input low voltage	V _{DD} =3.3V	-0.3		0.8	V
V _{IH}	Input high voltage	V _{DD} =2.5V	1.7		V _{DD} +0.3	V
V _{IL}	Input low voltage	$V_{\rm DD}$ =2.5 V	-0.3		0.7	V

DC Electrical Specifications- LVPECL Outputs

Parameter	Description	Conditions	Min.	Тур.	Max.	Units
V _{OH}	Output High voltage		V _{DDO} -1.4		V _{DDO} -0.9	V
V _{OL} Output Low voltage	Outroot I are solled	V _{DD} =2.5V	V _{DDO} -1.9		V _{DDO} -1.25	V
	V _{DD} =3.3V	V _{DDO} -2.2		V _{DDO} -1.25	V	

AC Electrical Specifications – Differential Inputs

Parameter	Description	Conditions	Min.	Тур.	Max.	Units
F _{IN}	Clock input frequency				2000	MHz
V _{INPP}	Differential Input peak to peak voltage	$1.5 \text{GHz} \le F_{IN} \le 2 \text{ GHz}$	0.2		1.5	V
		$F_{IN} \le 1.5 \text{ GHz}$	0.1		1.5	V
ER	Input Edge Rate		1.5			V/ns

AC Electrical Specifications – LVCMOS Inputs

Parameter	Description	Conditions	Min.	Тур.	Max.	Units
F _{IN}	Clock input frequency				200	MHz
***	Differential Input peak to peak voltage	$1.5 \text{GHz} \le F_{IN} \le 2 \text{ GHz}$	0.2		1.5	V
V _{INPP}		$F_{IN} \le 1.5 \text{ GHz}$	0.1		1.5	V
ER	Input Edge Rate		1.5			V/ns





AC Electrical Specifications – LVPECL Outputs

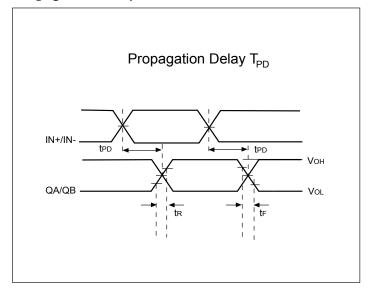
Parameter	Description	Conditions	Min.	Тур.	Max.	Units
F _{OUT}	Clock output frequency	LVPECL			2000	MHz
T _r	Output rise time	From 20% to 80%		150		ps
T_{f}	Output fall time	From 80% to 20%		150		ps
Todo	Output duty cycle		48		52	%
V _{PP}	Output swing Single-ended	@1GHz to ≤2GHz	250		850	mV
		@ ≤1GHz	500		950	mV
	Buffer additive jitter RMS	156.25MHz, 12kHz to 20MHz		0.01		ps
Tj		156.25MHz, 10kHz to 1MHz		0.01		ps
T_{SK}	Output Skew			13	30	ps
T_{PD}	Propagation Delay				750	ps
T _{OD}	Valid to HiZ				100	ns
Toe	HiZ to valid				100	ns
T _{P2P} Skew	Part to Part Skew ¹		-50		50	ps
V _{REF_AC}	Input bias voltage	$I_{AC} = 2mA$	V _{DD} -1.6		V _{DD} -1.1	V

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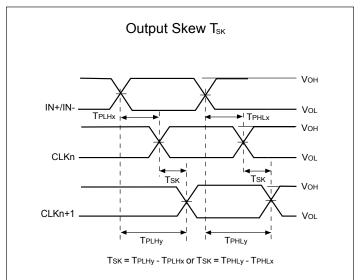




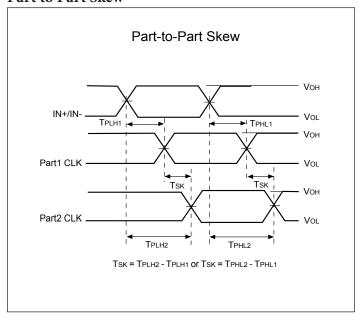
Propagation Delay



Output Skew



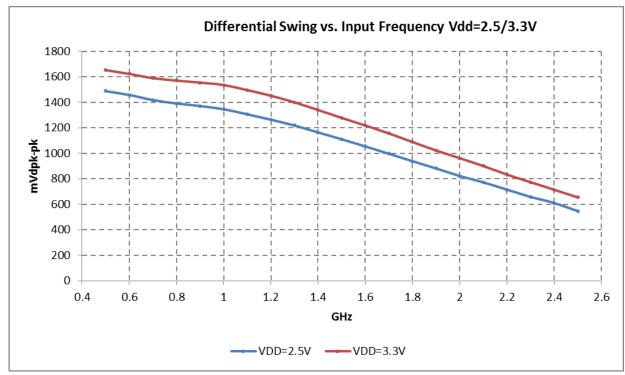
Part to Part Skew







LVPECL Output Swing vs. Frequency



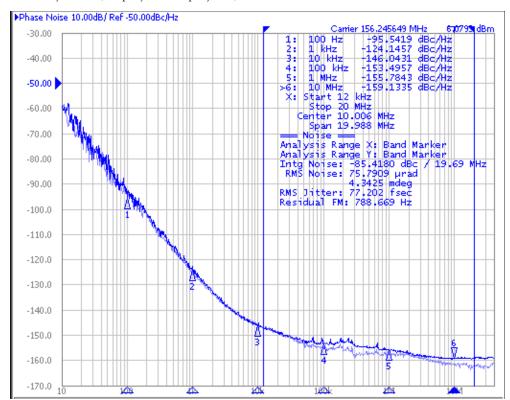
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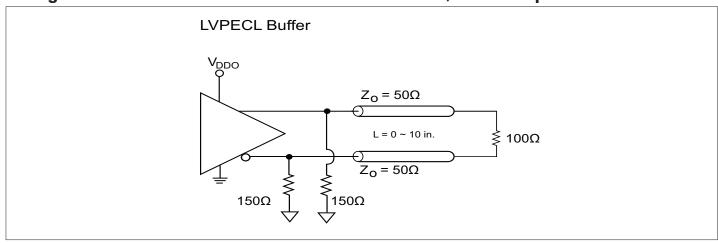


Phase Noise and Additive Jitter

Output phase noise (Dark Blue) vs Input Phase noise (light blue) Additive jitter = $\sqrt{\text{(Output jitter}^2 - Input jitter}^2)}$



Configuration Test Load Board Termination for LVPECL/ LVDS Outputs

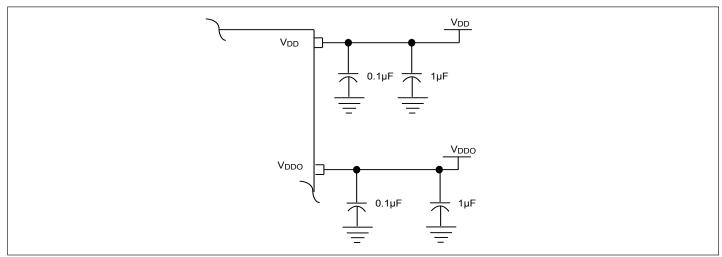






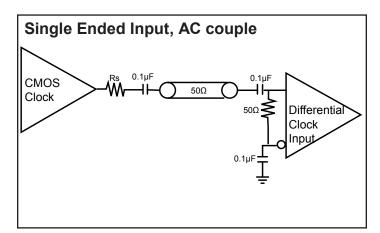
Power Supply Filtering Techniques

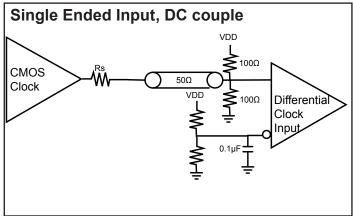
As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. All power pins should be individually connected to the power supply plane through vias, and $0.1\mu F$ an $1\mu F$ bypass capacitors should be used for each pin.

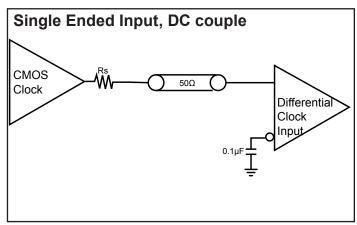


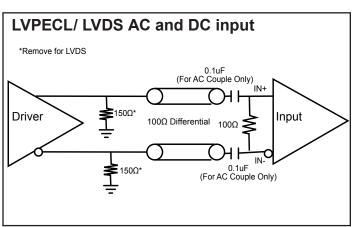


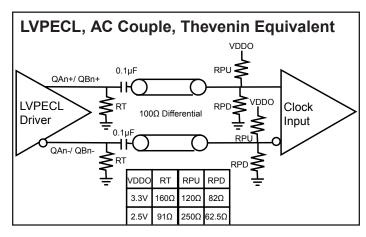


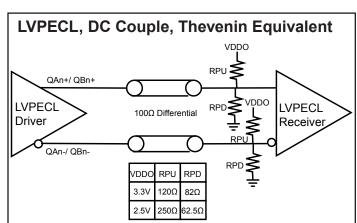








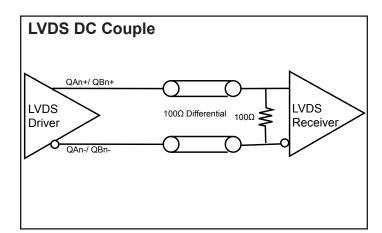


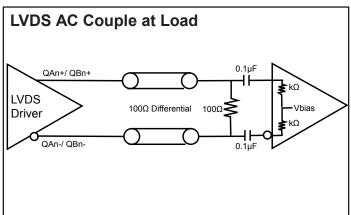


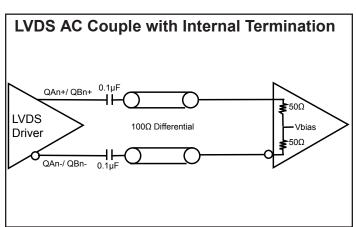
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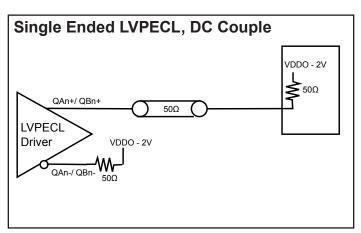


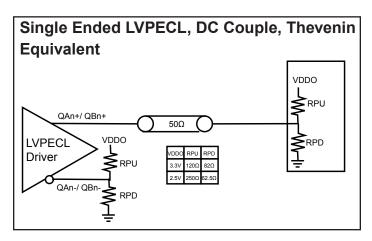


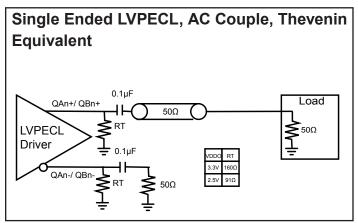












Thermal Information

Symbol	Description	Condition	
$\Theta_{ m JA}$	Junction-to-ambient thermal resistance	Still air	26.18 °C/W
$\Theta_{ m JC}$	Junction-to-case thermal resistance		10.52 °C/W





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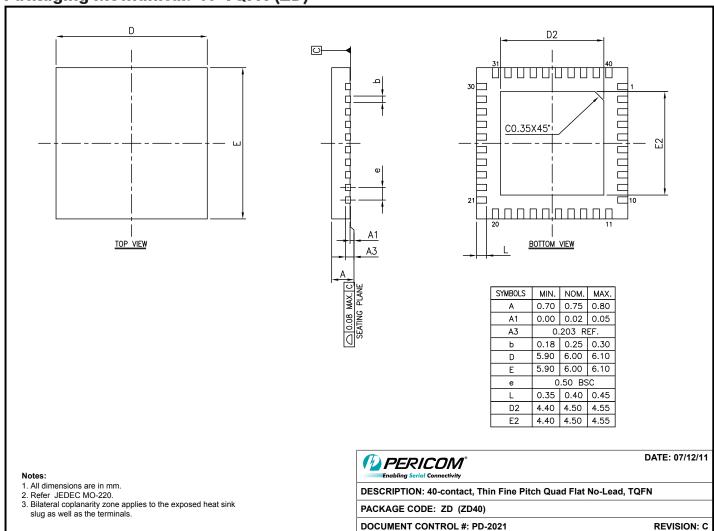
Part Marking

Top mark not available at this time. To obtain advance information regarding the top mark, please contact your local sales representative.





Packaging Mechanical: 40-TQFN (ZD)



For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Type	Operating Temperature
PI6C5912012ZDIEX	ZD	40-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)	-40 °C to 85 °C

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See http://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/
- 3. E = Pb-free and Green
- 4. X suffix = Tape/Reel





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